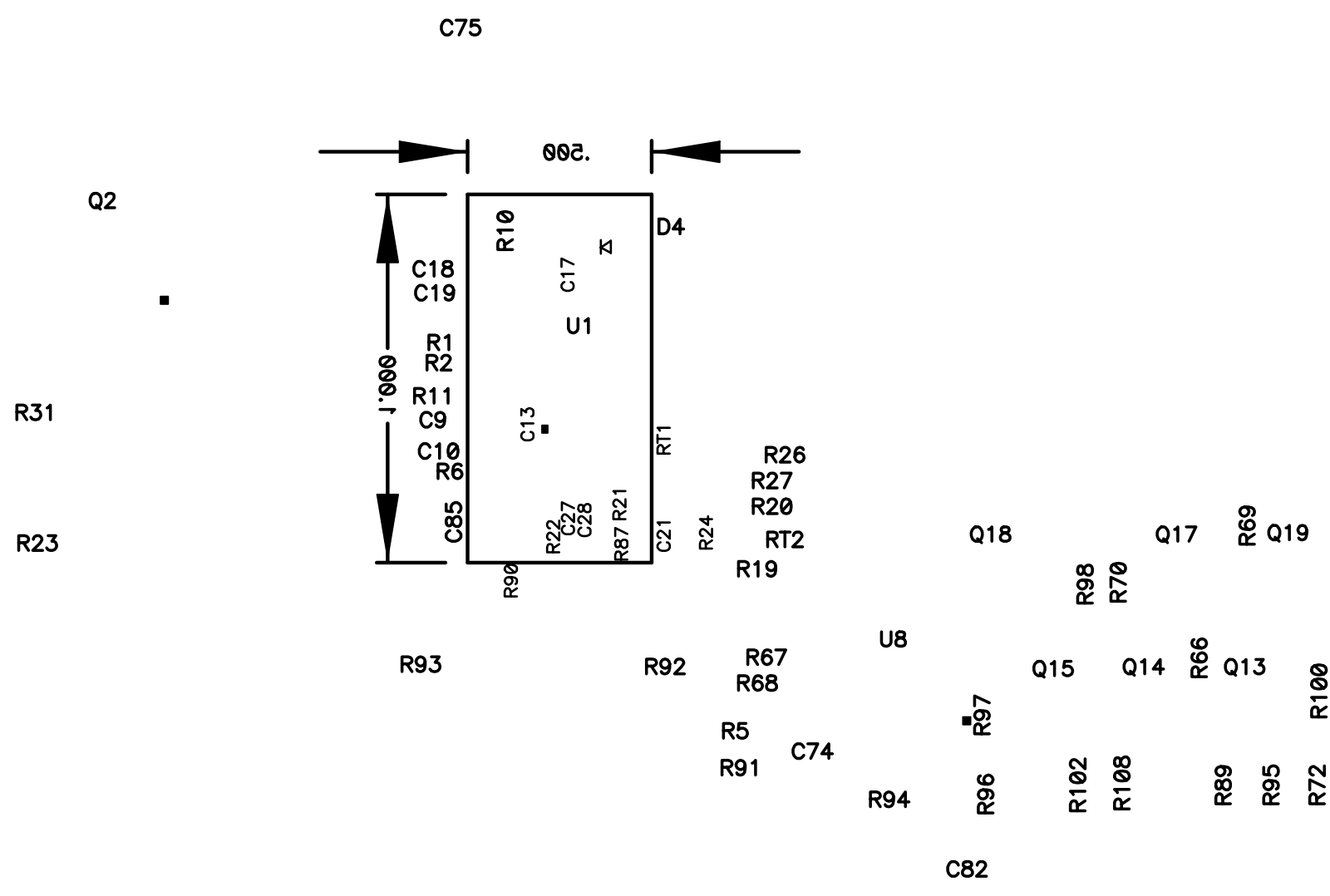
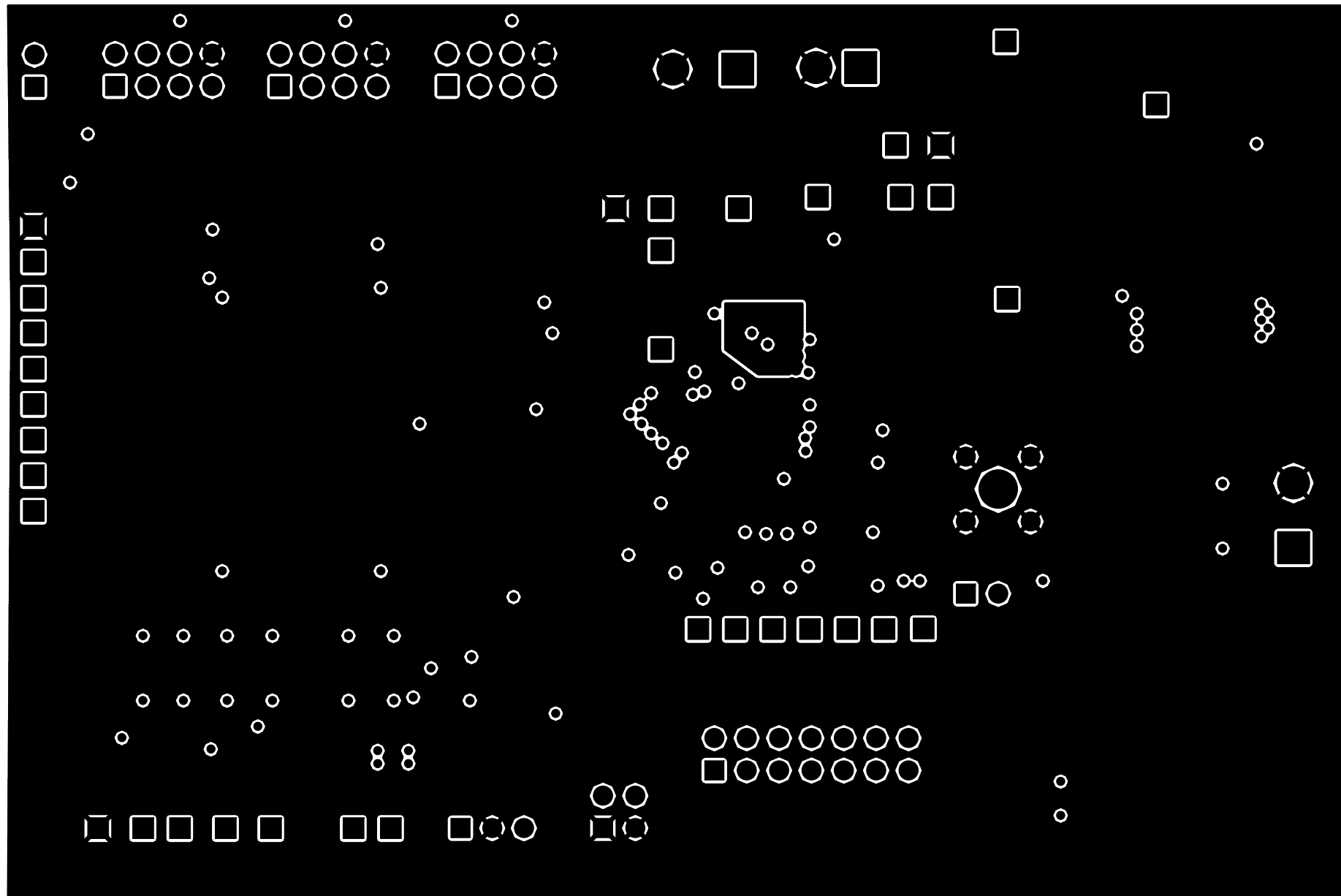


Date: OCT.1,2009		File Name: PMP5114rev.bcp		Engineer: JOSH MANDEL CORN		PCB Design: ROY SMITH		Modified Date: Tue Nov 03, 2009				Time Stamp: 14:05:37	
Board No. PMP5114		Rev. B		Copper Layer Name		Silkscreen		2 Mask		P Mask		Assembly	
Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	Fab Drawing
								M4					

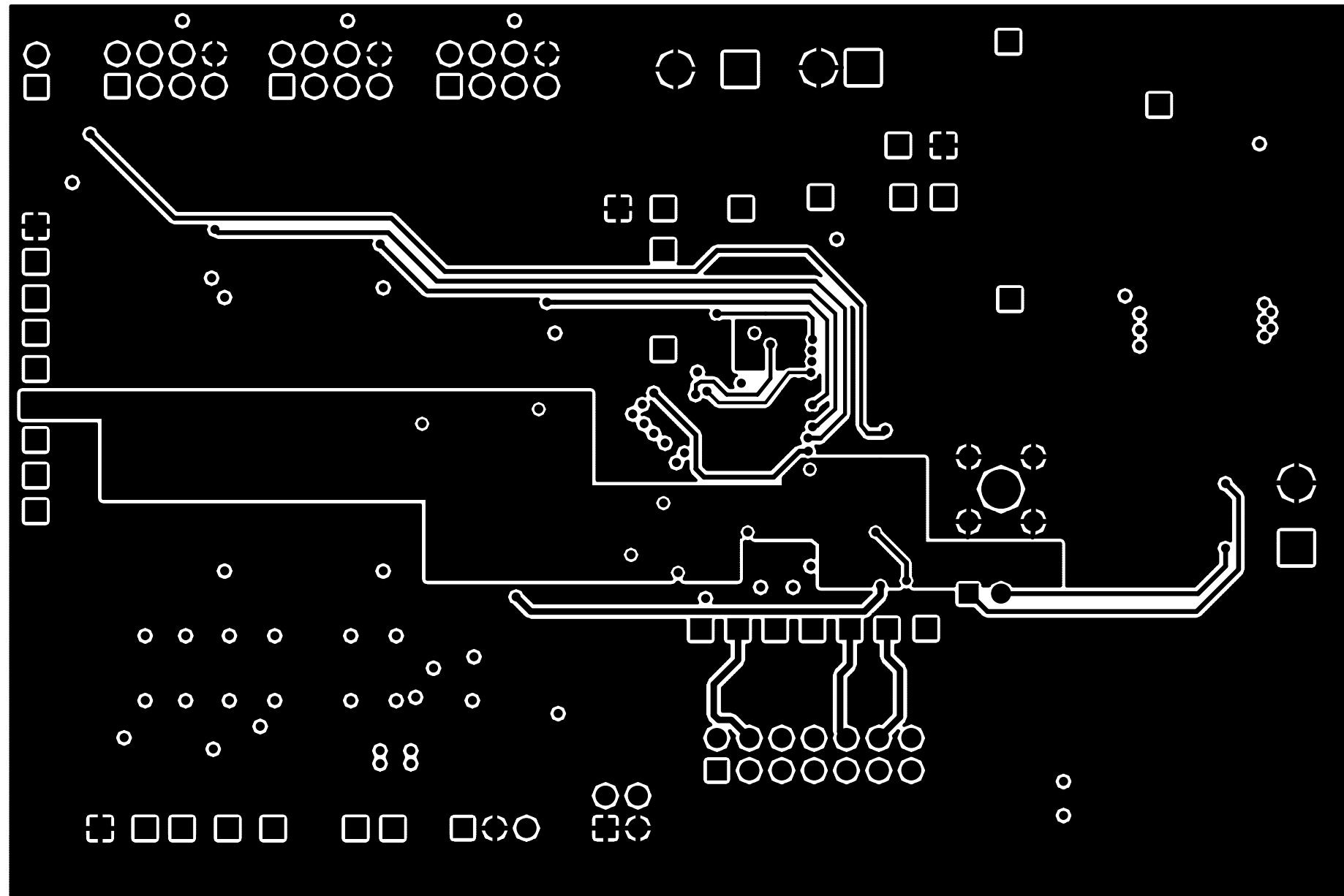


Date: OCT.1, 2009		File Name: PMP2114rev.bcp		Engineer: JOSH MANDEL CORN		PCB Design: ROY SMITH		Modified Date: The Nov 03, 2009		Time Stamp: 14:05:37	
Board No. PMP2114		Rev. B		Copper Layer Name		Silkscreen		P Mask		Assembly	
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				Bot		Bot		Bot		Bot	
				Bot		Bot		Bot		Bot	

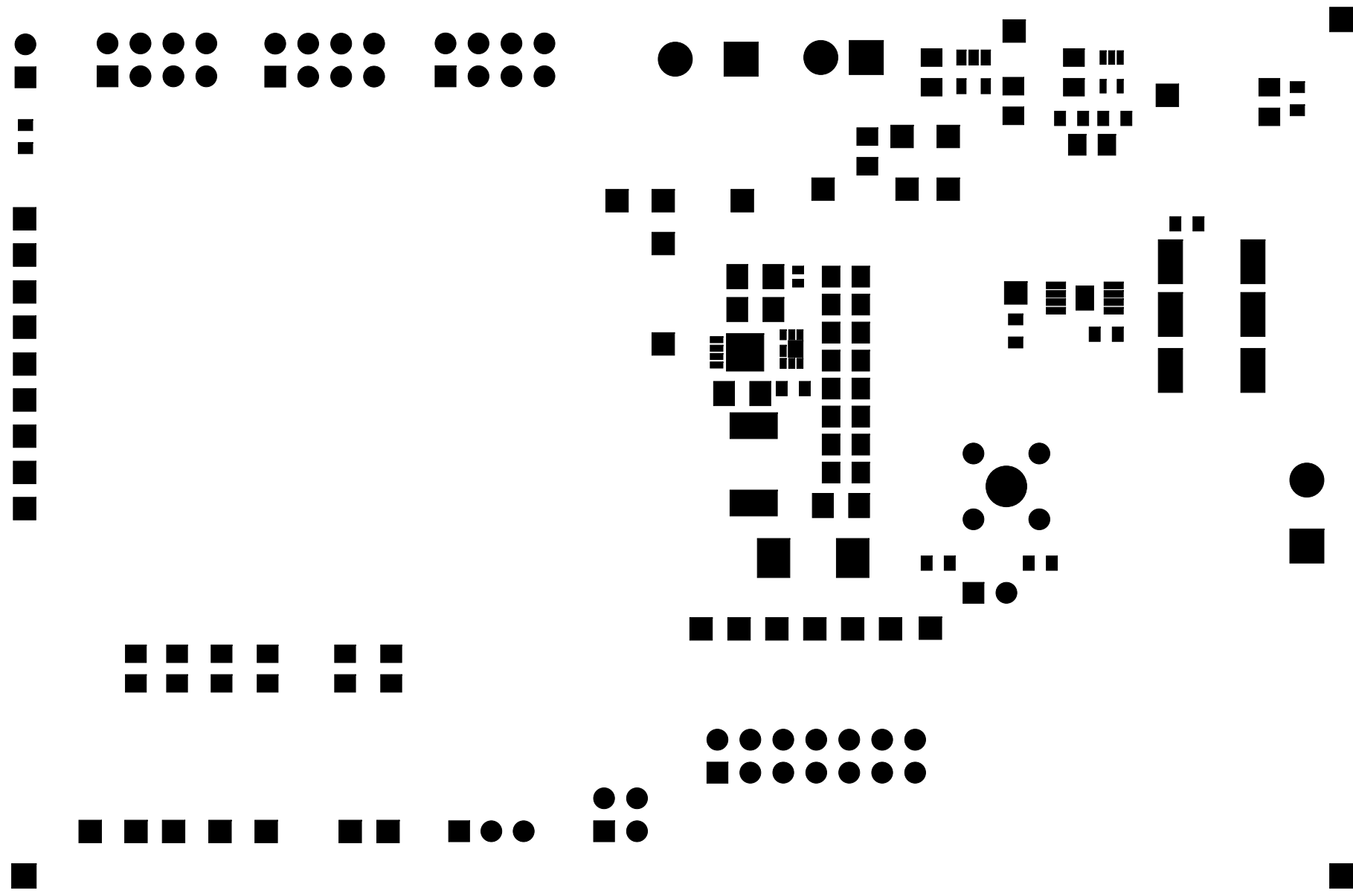




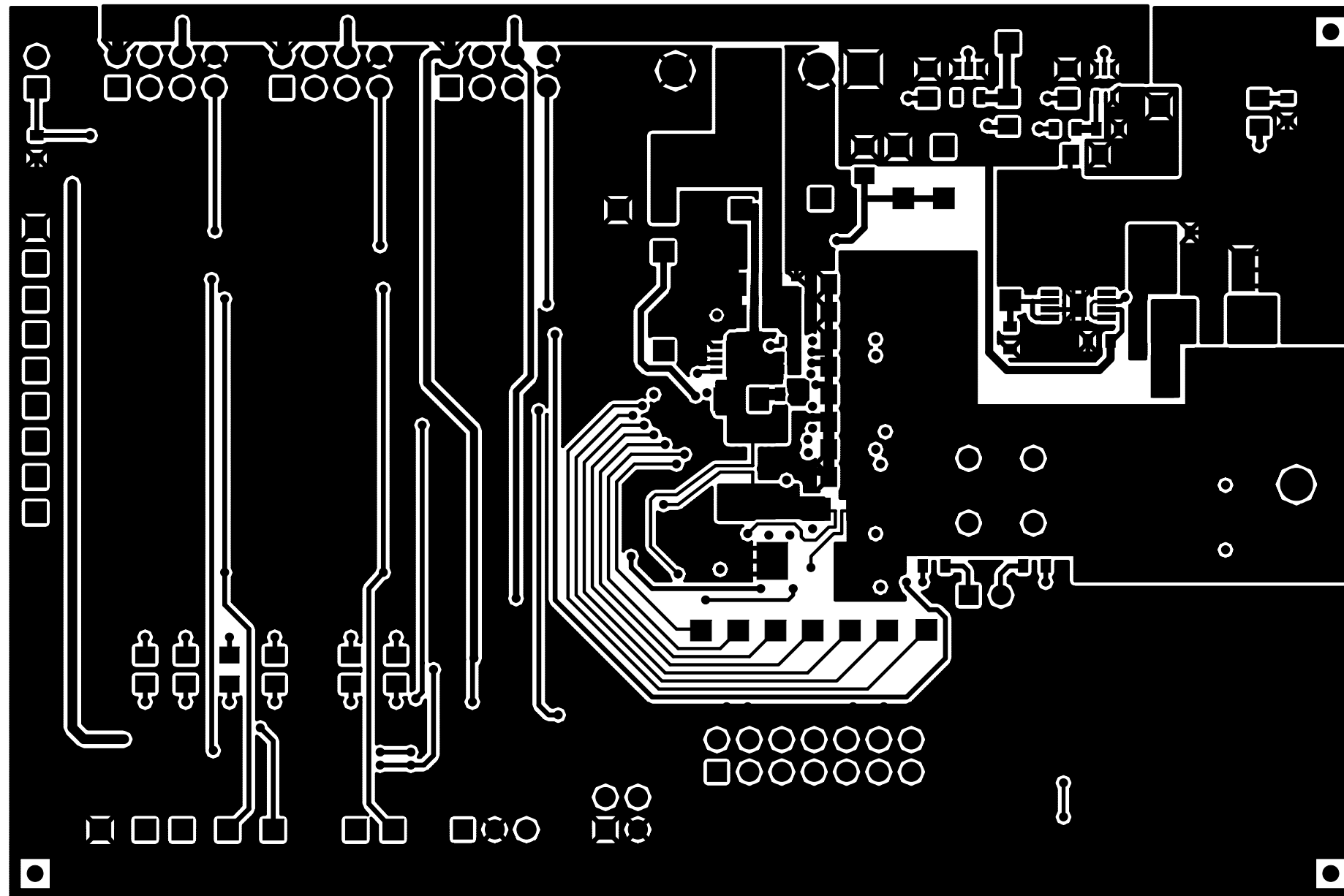
TEXAS INSTRUMENTS		Copper Layer Name			Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
		Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No.	Rev.		L2										
PMP5114	B												
Date: OCT.1,2009	Filename: PMP5114revB.pcb	Engineer: JOSH MANDELCORN	PCB Dsgnr: ROY SMITH	Modified Date: Tue Nov 03, 2009				Time Stamp: 14:02:37					



TEXAS INSTRUMENTS		Copper Layer Name			Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
		Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. <b>PMP5114</b>	Rev. <b>B</b>			<b>L3</b>									
Date: <b>OCT.1,2009</b>	Filename: <b>PMP5114revB.pcb</b>	Engineer: <b>JOSH MANDELCORN</b>	PCB Dsgnr: <b>ROY SMITH</b>	Modified Date: <b>Tue Nov 03, 2009</b>	Time Stamp: <b>14:02:37</b>								



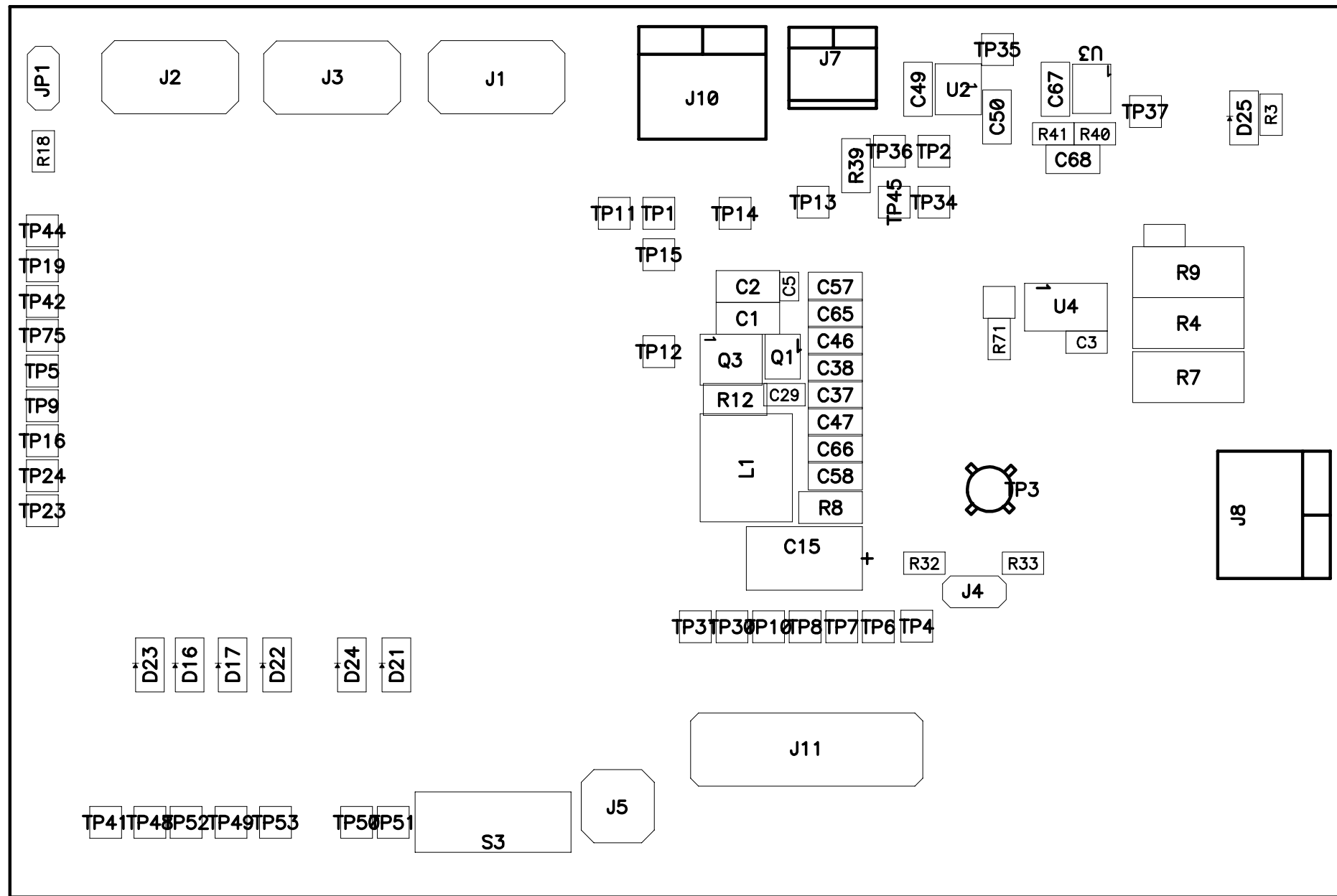
TEXAS INSTRUMENTS		Copper Layer Name			Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
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Board No. PMP5114	Rev. B						M1						
Date: OCT.1,2009	Filename: PMP5114revB.pcb	Engineer: JOSH MANDELCORN	PCB Dsgnr: ROY SMITH	Modified Date: Tue Nov 03, 2009				Time Stamp: 14:02:37					



TEXAS INSTRUMENTS		Copper Layer Name			Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
		Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PMP5114	Rev. B	L1											
Date: OCT.1,2009	Filename: PMP5114revB.pcb	Engineer: JOSH MANDELCORN	PCB Dsgnr: ROY SMITH	Modified Date: Tue Nov 03, 2009	Time Stamp: 14:02:37								

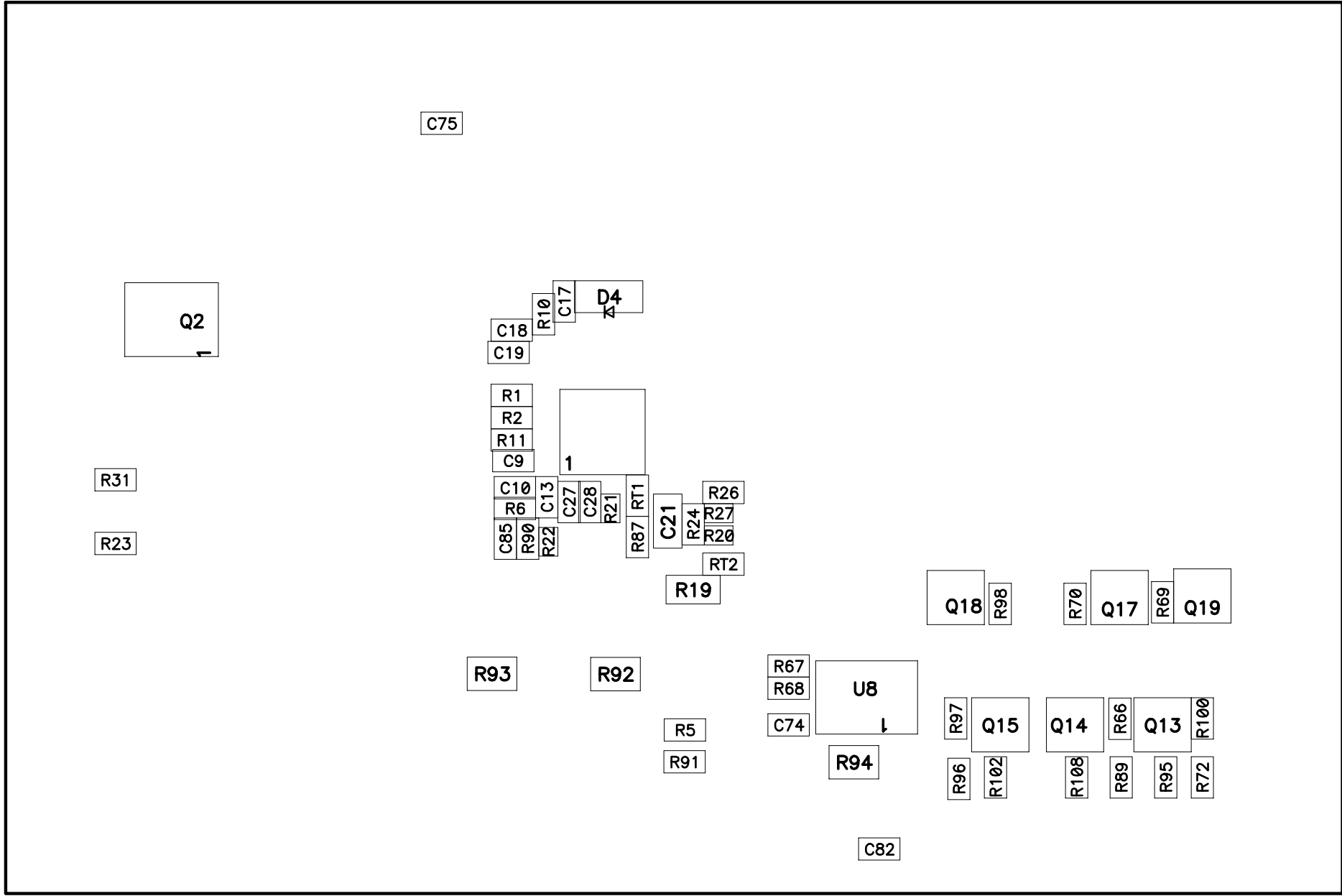






TEXAS INSTRUMENTS		Copper Layer Name			Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
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Board No.	Rev.												
PMP5114	B												
Date: OCT.1,2009	Filename: PMP5114revB.pcb	Engineer: JOSH MANDELCORN	PCB Dsgnr: ROY SMITH	Modified Date: Tue Nov 03, 2009	Time Stamp: 14:09:34								

Date: OCT.1, 2009		File Name: PMP2114rev.bcp		Engineer: JOSH MANDEL CORN		PCB Design: ROY SMITH		Modified Date: The Nov 03, 2009		Time Stamp: 14:09:34	
Board No. PMP2114		Rev. B		Copper Layer Name		Silkscreen		2 Mask		P Mask	
Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	Assembly
											Fab Drawing



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